

L Number	Hits	Search Text	DB	Time stamp
9	8	("4082394" "4322778" "5355283" "5537051" "5652185" "5777381" "5977617" "5994773").PN.	USPAT	2002/05/31 07:59
10	2	((("4082394" "4322778" "5355283" "5537051" "5652185" "5777381" "5977617" "5994773").PN.) and thermal	USPAT	2002/05/31 07:59
-	5939	semiconductor adj chip and resin	USPAT; US-PGPUB	2002/05/29 17:48
-	1754	(semiconductor adj chip and resin) and encapsulat\$3	USPAT; US-PGPUB	2002/05/29 17:48
-	147	((semiconductor adj chip and resin) and encapsulat\$3) and adhesive adj tape	USPAT; US-PGPUB	2002/05/30 18:53
-	60	((semiconductor adj chip and resin) and encapsulat\$3) and pressure adj2 adhesive	USPAT; US-PGPUB	2002/05/29 17:58
-	34	("3908075" "4410905" "4539472" "4595945" "4598308" "4616413" "4754319" "4796078" "4862245" "4937203" "4965654" "4996587" "5070390" "5075252" "5099309" "5140404" "5162264" "5170328" "5177032" "5218229" "5220195" "5227232" "5227338" "5227662" "5237201" "5250839" "5306670" "5349234" "5350947" "5382830" "5399903" "5412247" "5428247" "5481436").PN.	USPAT	2002/05/29 17:54
-	8	5696032.URPN.	USPAT	2002/05/29 17:56
-	123	((semiconductor adj chip and resin) and encapsulat\$3) and adhesive adj tape) not	USPAT; US-PGPUB	2002/05/29 17:59
-	1211	((semiconductor adj chip and resin) and encapsulat\$3) and pressure adj2 adhesive)	USPAT; US-PGPUB	2002/05/29 18:00
-	552	((semiconductor adj chip and resin) and encapsulat\$3) and (adhesive or tape)	USPAT; US-PGPUB	2002/05/29 17:59
-	362	lead adj frame	USPAT; US-PGPUB	2002/05/29 18:03
-	76	((semiconductor adj chip and resin) and encapsulat\$3) and (adhesive or tape)) and lead adj frame) and (tape)	USPAT; US-PGPUB	2002/05/29 18:01
-	241	((semiconductor adj chip and resin) and encapsulat\$3) and adhesive adj tape) not	USPAT; US-PGPUB	2002/05/29 18:03
-	40866	((semiconductor adj chip and resin) and encapsulat\$3) and pressure adj2 adhesive)) and lead adj frame	USPAT; US-PGPUB	2002/05/29 18:04
-	1183	pressure adj sensitive) and thermal adj (shrinkage or expansion)	USPAT; US-PGPUB	2002/05/29 18:04
-	120	(pressure adj sensitive) same thermal adj (shrinkage or expansion)	USPAT; US-PGPUB	2002/05/29 18:11
-	9	("3725115" "4379201" "4574879" "4714655" "4869879" "4908296" "5213868" "5366573" "5462977").PN.	USPAT	2002/05/29 18:11
-	0	((("3725115" "4379201" "4574879" "4714655" "4869879" "4908296" "5213868" "5366573" "5462977").PN.) same thermal adj (shrinkage or expansion)	USPAT; US-PGPUB	2002/05/29 18:19
-	0	((("3725115" "4379201" "4574879" "4714655" "4869879" "4908296" "5213868" "5366573" "5462977").PN.) same thermal adj (contraction)	USPAT; US-PGPUB	2002/05/29 18:19
-	0	(pressure adj sensitive) same thermal adj (contraction)	USPAT; US-PGPUB	2002/05/29 18:19
-	25536	semiconductor adj chip	USPAT; US-PGPUB	2002/05/30 19:19

-	3186	(semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage)	USPAT; US-PGPUB	2002/05/30 19:19
-	292	(semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage) with (tape or adhesive)	USPAT; US-PGPUB	2002/05/30 19:06
-	383	(semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage) with (tape or film)	USPAT; US-PGPUB	2002/05/30 19:11
-	220	(semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage) near5 (tape or film)	USPAT; US-PGPUB	2002/05/30 19:08
-	220	((semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage) with (tape or film)) and thermal adj (expansion or contraction or shrinkage) near5 (tape or film)	USPAT; US-PGPUB	2002/05/30 19:14
-	40	((semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage) with (tape or film)) and thermal adj (expansion or contraction or shrinkage) near5 (tape or film)) and "%"	USPAT; US-PGPUB	2002/05/30 19:17
-	4	((semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage) with (tape or film)) and thermal adj (expansion or contraction or shrinkage) near5 (tape or film)) and "%" with thermal	USPAT; US-PGPUB	2002/05/30 19:17
-	42359	semiconductor adj chip	EPO; JPO; DERWENT	2002/05/30 19:19
-	1109	(semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage)	EPO; JPO; DERWENT	2002/05/30 19:19
-	167	(semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage) with (tape or film or adhesive)	EPO; JPO; DERWENT	2002/05/30 19:29
-	1	("6284566").PN.	USPAT; US-PGPUB	2002/05/30 19:29
-	8	("4082394" "4322778" "5355283" "5537051" "5652185" "5777381" "5977617" "5994773").PN.	USPAT	2002/05/31 07:59